



PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2811**

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[Signature]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazuo TANAKA

Group Art Unit: 2811

Application No.: 09/586,963

Examiner: C. Q. Nguyen

Filed: June 5, 2000

Docket No.: 039894.01

For: SEMICONDUCTOR DEVICE AND A METHOD FOR MAKING THE SAME THAT
PROVIDE ARRANGEMENT OF A CONNECTING REGION FOR AN EXTERNAL
CONNECTING TERMINAL

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the February 26, 2003 Office Action, please amend the above-identified
application as follows:

IN THE CLAIMS:

Please replace claim 2 as follows:

- E1
2. (Five Times Amended) A semiconductor device including a bonding pad,
wherein the bonding pad is a multiple wiring layer structure, the bonding pad comprising:
a first conductive layer connected to a conductive member for external
connection;
a second conductive layer disposed below said first conductive layer, the
second conductive layer having a plurality of openings;

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